

LISTING OF CLAIMS

1-12. (Canceled without prejudice).

13. (Original) A method for forming the magnetic random access memory comprising the steps of:

etching a semiconductor substrate by photolithography using an active mask to form a circular pillar, the semiconductor having a top surface;

forming a gate oxide layer on the entire top surface of the semiconductor substrate;

performing ion implantation of a high concentration impurity on the substrate and on a top portion of the circular pillar by a drive-in process, thereby forming a drain junction region on the upper side of the circular pillar and a source junction region on the bottom of the circular pillar extending into the substrate surface;

forming a first word line of a gate electrode by forming a planarized conductor layer for the gate electrode exposing the drain junction region and then patterning the planarized conductor layer;

forming a planarized first interlayer insulation layer;

forming a contact line contacting the drain junction region through the first interlayer insulation layer;

forming a semi-magnetic layer, a pinned ferromagnetic layer, a tunnel junction layer, and a free ferromagnetic layer above the contact line;

forming a magnetic tunnel junction cell by patterning the semi-magnetic layer, the pinned ferromagnetic layer, the tunnel junction layer, and the free ferromagnetic layer by photolithography using a magnetic tunnel junction cell mask;

forming a planarized second interlayer insulation layer exposing the magnetic tunnel junction cell;

forming a bit line contacting the free ferromagnetic layer; and

forming a second word line over the magnetic tunnel junction cell and above the bit line.

14. (Original) The method of claim 13, wherein the step of performing ion implantation of the high concentration impurity is performed with an energy of more than 30 KeV and at a dose of more than $5E14$ ions/cm².

15. (Original) The method of claim 13, wherein the second word line is parallel to and has the same width as the first word line.

16. (Original) A method for forming the magnetic random access memory comprising the steps of:

etching a semiconductor substrate by photolithography using an active mask thereby forming a circular pillar extending above a top surface of the substrate;

forming a gate oxide layer on the entire top surface of the substrate;

performing an ion implantation of a high concentration impurity and drive-in processes, thereby forming a drain junction region on an upper portion of the circular pillar and a source junction region on a bottom portion of the circular pillar and on the substrate;

forming a conductor layer for a gate electrode at a predetermined thickness on the substrate, and performing an anisotropic etching process, thereby forming a gate electrode in the form of a conductor spacer at a sidewall of the circular pillar;

forming a planarized first interlayer insulation layer;

forming a contact line contacting the drain junction region through the first interlayer insulation layer;

forming a semi-magnetic layer, a pinned ferromagnetic layer, a tunnel junction layer, and a free ferromagnetic layer above the contact line;

forming the magnetic tunnel junction cell by patterning the semi-magnetic layer, the pinned ferromagnetic layer, the tunnel junction layer, and the free ferromagnetic layer by photolithography using a magnetic tunnel junction cell mask;

forming a planarized second interlayer insulator exposing the magnetic tunnel junction cell;

forming a bit line contacting the free ferromagnetic layer; and

forming a second word line over an upper portion of the magnetic tunnel junction cell and above the bit line.

17. (Original) The method of claim 16, wherein the step of performing ion implantation of the high concentration impurity is performed with an energy of more than 30 KeV, at a dose of more than 5×10^{14} ions/cm².

18. (Original) The method of claim 16, wherein the gate electrode is a first word line and wherein the steps of claim 16 are repeated to form a plurality of magnetic random access memories a plurality of first word lines, a plurality of circular pillars, and a plurality of second word lines, wherein the plurality of first word lines are spaced apart a distance that is 1.5 times larger than the distance between the plurality of circular pillars along one of said plurality of first word lines or along one of said plurality of the second word lines, by anisotropically etching the conductor layers for the plurality of first word lines without using separate masks.

19. (Original) The method of claim 17, wherein the first word line and the second word line have equal width.